

sub c1 21. (Amended) The semiconductor package of Claim 20 wherein:

each of the leads defines opposed first and second surfaces and a third surface which is opposed to the second surface, the first surface being oriented between the second and third surfaces;

B2 the bond pads of the first semiconductor die are electrically connected to respective ones of the first surfaces of the leads by first conductive wires; and

the bond pads of the second semiconductor die are electrically connected to respective ones of the second surfaces of the leads by second conductive wires.